

## Features

- Very low FOM  $R_{DS(on)} \times Q_g$
- 100% avalanche tested

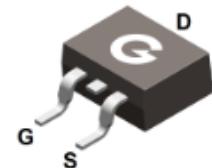
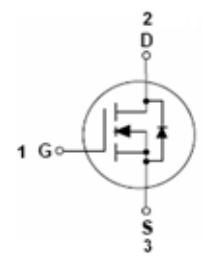
**HF**

## APPLICATIONS

- SMPS
- UPS
- PFC

## Mechanical Data

- Case: TO-263
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



**TO-263**

## Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
SJ80R350B	TO-263	50 pcs / Tube & 800 pcs / Tape & Reel	SJ80R350B

## Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	$V_{DSS}$	800	V
Gate-to-Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	15	A
Pulsed Drain Current *1	$I_{DM}$	45	A
Single Pulse Avalanche Energy *2	$E_{AS}$	324	mJ
Avalanche Current *1	$I_{AR}$	4	A
Repetitive Avalanche Energy *1	$E_{AR}$	0.75	mJ

## Thermal Characteristics

Parameter	Symbol	Value	Unit
Power Dissipation	$P_D$	34	W
Thermal Resistance Junction-to-Air	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	0.83	$^\circ\text{C}/\text{W}$
Operating Junction Temperature Range	$T_J$	-55 ~ +150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 ~ +150	$^\circ\text{C}$

**Electrical Characteristics** (@  $T_J = 25^\circ\text{C}$  unless otherwise specified)

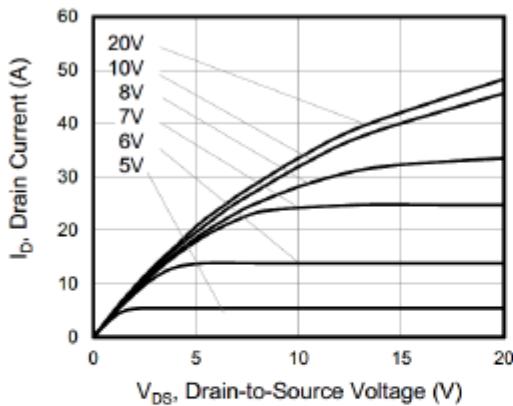
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
$V_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	800	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 800\text{V}, V_{GS} = 0\text{V}, T_J = 25^\circ\text{C}$	-	-	1	$\mu\text{A}$
		$V_{DS} = 800\text{V}, V_{GS} = 0\text{V}, T_J = 150^\circ\text{C}$	-	-	100	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$R_{DS(ON)}$	Static Drain-Source On-resistance <sup>*3</sup>	$V_{GS} = 10\text{V}, I_D = 7.5\text{A}$	-	0.26	0.35	$\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.5	-	4.5	V
$g_f$	Forward Transconductance <sup>*3</sup>	$V_{GS} = 10\text{V}, I_D = 7.5\text{A}$	-	18.8	-	S
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{GS} = 0\text{V}$ $V_{DS} = 50\text{V}$ $f = 1.0\text{MHz}$	-	2330	-	pF
$C_{oss}$	Output Capacitance		-	116	-	
$C_{rss}$	Reverse Transfer Capacitance		-	7	-	
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = 400\text{V}$ $R_G = 25\Omega$ $I_D = 15\text{A}$	-	43	-	ns
$t_r$	Turn-on Rise Time		-	14	-	
$t_{d(off)}$	Turn-Off Delay Time		-	150	-	
$t_f$	Turn-Off Fall Time		-	7	-	
$Q_G$	Total Gate-Charge	$V_{DD} = 640\text{V}$ $V_{GS} = 10\text{V}$ $I_D = 15\text{A}$	-	46	-	nC
$Q_{GS}$	Gate to Source Charge		-	11	-	
$Q_{GD}$	Gate to Drain (Miller) Charge		-	13	-	
<b>Source-Drain Diode Characteristics</b>						
$V_{SD}$	Diode Forward Voltage	$I_{SD} = 15\text{A}, V_{GS} = 0\text{V}, T_J = 25^\circ\text{C}$	-	0.9	1.2	V
$I_S$	Diode Continuous Forward Current	$T_c = 25^\circ\text{C}$	-	-	15	A
$I_{SM}$	Pulsed Source-Drain Current		-	-	45	A
$t_{rr}$	Reverse Recovery Time	$I_S = I_F, V_R = 400\text{V}$ $di/dt = 100\text{ A}/\mu\text{s}$	-	460	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	3.8	-	$\mu\text{C}$

Notes:

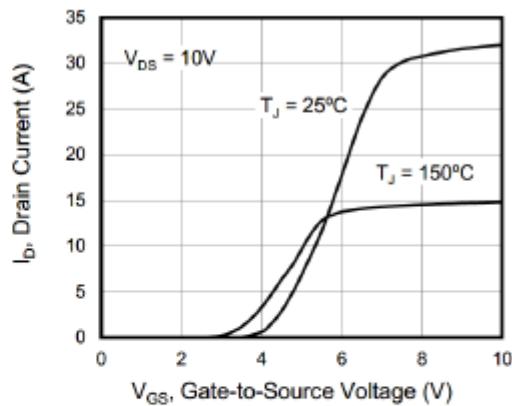
1. Repetitive Rating: Pulse width limited by maximum junction temperature
2.  $I_{AS} = 4\text{A}, V_{DD} = 50\text{V}, R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$
3. Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 1\%$

### Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

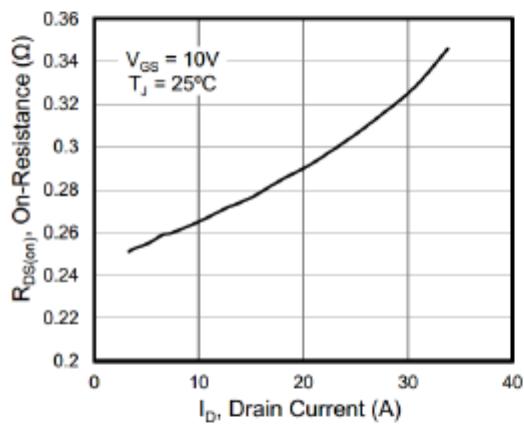
**Figure 1. Output Characteristics**



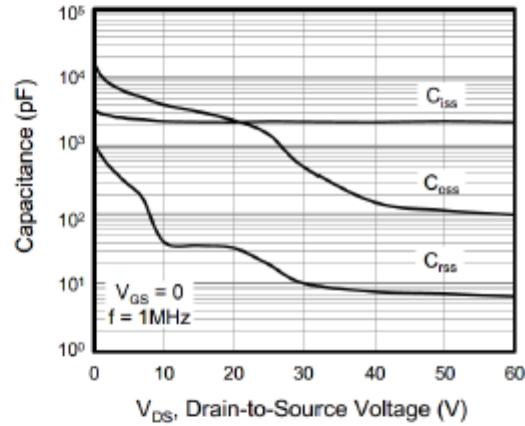
**Figure 2. Transfer Characteristics**



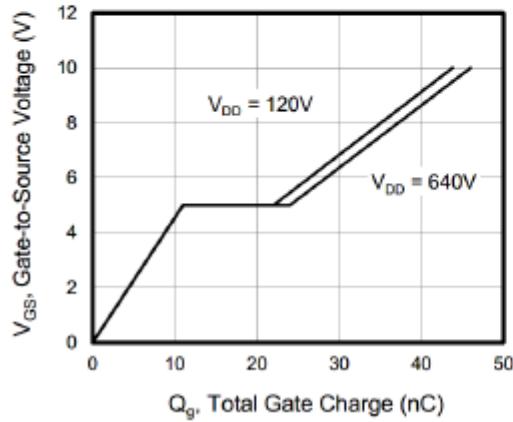
**Figure 3. On-Resistance vs. Drain Current**



**Figure 4. Capacitance**



**Figure 5. Gate Charge**



**Figure 6. Body Diode Forward Voltage**

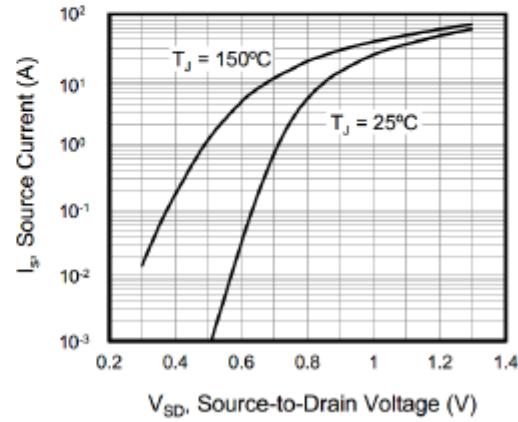


Figure 7. On-Resistance vs.  
Junction Temperature

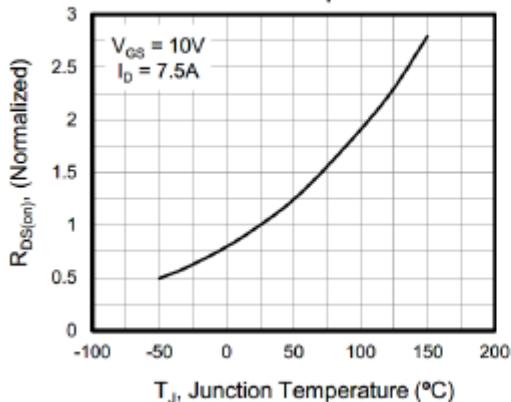
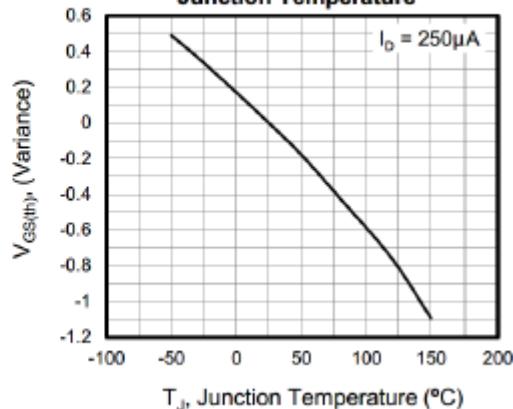
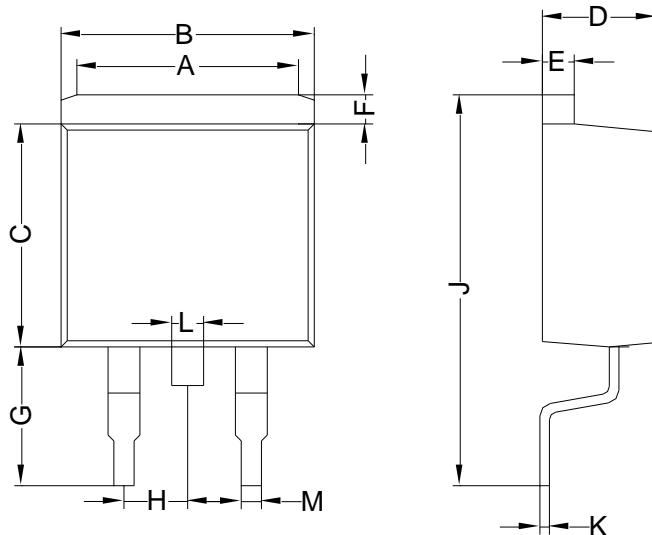


Figure 8. Threshold Voltage vs.  
Junction Temperature



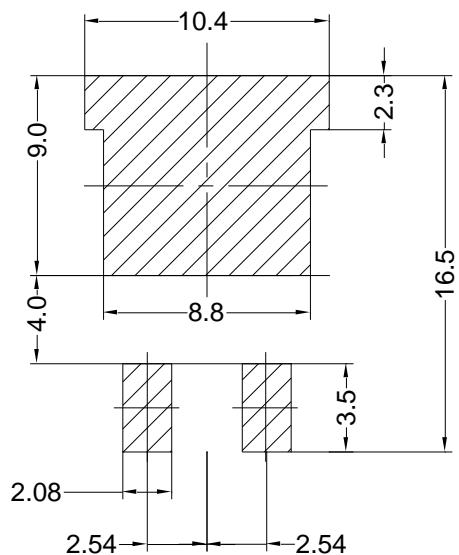
## Package Outline Dimensions (Unit: mm)



TO-263		
Dimension	Min.	Max.
A	6.00	8.00
B	9.90	10.30
C	8.50	9.10
D	4.37	4.77
E	1.07	1.47
F	1.07	1.47
G	5.34	5.74
H	2.44	2.64
J	15.30	15.90
K	0.28	0.48
L	1.17	1.37
M	0.71	0.91

## Mounting Pad Layout (Unit: mm)

## TO-263



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